

DDR4 Connector



OVERVIEW

Luxshare-TECH's vertical DDR4 DIMM sockets provide 288 contacts on 0.85mm pitch. The DDR4 connector interface could be mated with the DDR4 memory modules that conform to JEDEC MO-309. The DDR4 family support Through Hole and SMT, two solder types. Various pin tail lengths for PCB thickness, compatible to different customer requirements. Luxshare-TECH DDR4 connectors could support multi-form of DDR4 modules including UDIMM, RDIMM and LRDIMM. Based on excellent performance and diverse options, Luxshare DDR4 product family are widely adopted in PCs, servers, workstations, storage, and embedded applications in communications and industrial equipment.

FEATURES & BENEFITS

- Through Hole and SMT options available, support diverse hardware design requirement
- Various pin tail lengths for different PCB thickness
- Lower insertion force, easier for module insertion and enough retention force for better reliability
- Narrow housing solutions,Saves board space and benefits air-flow

PRODUCT APPLICATIONS

Data center & Networking Equipment
Servers/Storage Devices
High Performance Computing (HPC)
Switches/Routers

INDUSTRY STANDARDS

TH: JEDEC SO-016B
SMT: JEDEC SO-017A

TECHNICAL INFORMATION

MATERIAL

Terminal: Copper Alloy
Contact Area Finish: Gold over Nickel
Solder Area Finish: Tin over Nickel
Board lock: Stainless steel, plated tin over nickel
Housing: High temperature thermoplastic(UL 94V-0)
Latch: High temperature thermoplastic(UL 94V-0)

ELECTRICAL PERFORMANCE

Voltage: 30V AC(RMS)/DC
Current: 0.75A MAX per contact
Differential Impedance: 50±5ohms

ENVIRONMENTAL

Operating temperature : -55°C TO +85°C
Storage temperature : +15°C TO +35°C
Relative humidity: 20% to 80%
Atmospheric pressure: 650mm to 800mm of Hg (86 ~106Kpa)

MECHANICAL PERFORMANCE

Rated Durability Cycles: 25
Mating Force: 0.37N /pin MAX
Unmating Force: 0.07N /pin MIN
Retention force- Terminal: 300gf/pin MIN
Retention force- Board lock: 13.3N /pin MIN
Insertion force - Connector to board: 7.65kgf MAX
Preheat: +150° to +180°C / 60~120 seconds
Reflow: +230° to +260°C / 30~60 seconds

PACKAGING

Tray

SPECIFICATION

ES-11-00-0003

Partial PN Table

Product Numbers	Product Description
PDRBB9-5300-003-0H	DDR4+288pin+SMT+30u" Au+MT+S-L,Tray+HF
PDRBB9-3300-000-0H	DDR4+288pin+TH+30u" Au+Boardlock+S-L
PDRBB9-3301-000-0H	DDR4+288pin+TH 25 °C+30u Au+with boardlock
PDRBB9-3302-000-0H	DDR4 TH 288Pin 30u" Au with Boardlock